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#### Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

#### Applications of **Embedded - Microprocessors**

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

#### Details

Product Status	Obsolete
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	50MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (2), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	-40°C ~ 95°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/kmpc860dtczq50d4

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## 2 Features

The following list summarizes the key MPC860 features:

- Embedded single-issue, 32-bit core (implementing the Power Architecture technology) with thirty-two 32-bit general-purpose registers (GPRs)
  - The core performs branch prediction with conditional prefetch without conditional execution.
  - 4- or 8-Kbyte data cache and 4- or 16-Kbyte instruction cache (see Table 1)
    - 16-Kbyte instruction caches are four-way, set-associative with 256 sets; 4-Kbyte instruction caches are two-way, set-associative with 128 sets.
    - 8-Kbyte data caches are two-way, set-associative with 256 sets; 4-Kbyte data caches are two-way, set-associative with 128 sets.
    - Cache coherency for both instruction and data caches is maintained on 128-bit (4-word) cache blocks.
    - Caches are physically addressed, implement a least recently used (LRU) replacement algorithm, and are lockable on a cache block basis.
  - MMUs with 32-entry TLB, fully-associative instruction, and data TLBs
  - MMUs support multiple page sizes of 4-, 16-, and 512-Kbytes, and 8-Mbytes; 16 virtual address spaces and 16 protection groups
  - Advanced on-chip-emulation debug mode
- Up to 32-bit data bus (dynamic bus sizing for 8, 16, and 32 bits)
- 32 address lines
- Operates at up to 80 MHz
- Memory controller (eight banks)
  - Contains complete dynamic RAM (DRAM) controller
  - Each bank can be a chip select or  $\overline{RAS}$  to support a DRAM bank.
  - Up to 15 wait states programmable per memory bank
  - Glueless interface to DRAM, SIMMS, SRAM, EPROM, Flash EPROM, and other memory devices
  - DRAM controller programmable to support most size and speed memory interfaces
  - Four  $\overline{\text{CAS}}$  lines, four  $\overline{\text{WE}}$  lines, and one  $\overline{\text{OE}}$  line
  - Boot chip-select available at reset (options for 8-, 16-, or 32-bit memory)
  - Variable block sizes (32 Kbytes to 256 Mbytes)
  - Selectable write protection
  - On-chip bus arbitration logic
- General-purpose timers
  - Four 16-bit timers or two 32-bit timers
  - Gate mode can enable/disable counting
  - Interrupt can be masked on reference match and event capture.



Features

- Allows dynamic changes
- Can be internally connected to six serial channels (four SCCs and two SMCs)
- Parallel interface port (PIP)
  - Centronics interface support
  - Supports fast connection between compatible ports on the MPC860 or the MC68360
- PCMCIA interface
  - Master (socket) interface, release 2.1 compliant
  - Supports two independent PCMCIA sockets
  - Supports eight memory or I/O windows
- Low power support
  - Full on-all units fully powered
  - Doze—core functional units disabled except time base decrementer, PLL, memory controller, RTC, and CPM in low-power standby
  - Sleep-all units disabled except RTC and PIT, PLL active for fast wake up
  - Deep sleep—all units disabled including PLL except RTC and PIT
  - Power down mode—all units powered down except PLL, RTC, PIT, time base, and decrementer
- Debug interface
  - Eight comparators: four operate on instruction address, two operate on data address, and two
    operate on data
  - Supports conditions: =  $\neq < >$
  - Each watchpoint can generate a break-point internally.
- 3.3-V operation with 5-V TTL compatibility except EXTAL and EXTCLK
- 357-pin ball grid array (BGA) package



# 3 Maximum Tolerated Ratings

This section provides the maximum tolerated voltage and temperature ranges for the MPC860. Table 2 provides the maximum ratings.

This device contains circuitry protecting against damage due to high-static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (for example, either GND or  $V_{DD}$ ).

(GND = 0 V)

## Table 2. Maximum Tolerated Ratings

Rating	Symbol	Value	Unit
Supply voltage <sup>1</sup>	V <sub>DDH</sub>	-0.3 to 4.0	V
	V <sub>DDL</sub>	-0.3 to 4.0	V
	KAPWR	-0.3 to 4.0	V
	V <sub>DDSYN</sub>	-0.3 to 4.0	V
Input voltage <sup>2</sup>	V <sub>in</sub>	GND – 0.3 to V <sub>DDH</sub>	V
Temperature <sup>3</sup> (standard)	T <sub>A(min)</sub>	0	°C
	T <sub>j(max)</sub>	95	°C
Temperature <sup>3</sup> (extended)	T <sub>A(min)</sub>	-40	°C
	T <sub>j(max)</sub>	95	°C
Storage temperature range	T <sub>stg</sub>	-55 to 150	°C

<sup>1</sup> The power supply of the device must start its ramp from 0.0 V.

<sup>2</sup> Functional operating conditions are provided with the DC electrical specifications in Table 6. Absolute maximum ratings are stress ratings only; functional operation at the maxima is not guaranteed. Stress beyond those listed may affect device reliability or cause permanent damage to the device.

**Caution**: All inputs that tolerate 5 V cannot be more than 2.5 V greater than the supply voltage. This restriction applies to power-up and normal operation (that is, if the MPC860 is unpowered, voltage greater than 2.5 V must not be applied to its inputs).

<sup>3</sup> Minimum temperatures are guaranteed as ambient temperature, T<sub>A</sub>. Maximum temperatures are guaranteed as junction temperature, T<sub>j</sub>.



	m Chavastavistis		MHz	40 MHz		50 MHz		66 MHz		
Num	Characteristic	Min	Max	Min	Max	Min	Max	Min	Max	Unit
B9	CLKOUT to A(0:31), BADDR(28:30), RD/WR, BURST, D(0:31), DP(0:3), TSIZ(0:1), REG, RSV, AT(0:3), PTR High-Z	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.04	ns
B11	CLKOUT to $\overline{TS}$ , $\overline{BB}$ assertion	7.58	13.58	6.25	12.25	5.00	11.00	3.80	11.29	ns
B11a	CLKOUT to $\overline{TA}$ , $\overline{BI}$ assertion (when driven by the memory controller or PCMCIA interface)	2.50	9.25	2.50	9.25	2.50	9.25	2.50	9.75	ns
B12	CLKOUT to $\overline{TS}$ , $\overline{BB}$ negation	7.58	14.33	6.25	13.00	5.00	11.75	3.80	8.54	ns
B12a	CLKOUT to $\overline{TA}$ , $\overline{BI}$ negation (when driven by the memory controller or PCMCIA interface)	2.50	11.00	2.50	11.00	2.50	11.00	2.50	9.00	ns
B13	CLKOUT to TS, BB High-Z	7.58	21.58	6.25	20.25	5.00	19.00	3.80	14.04	ns
B13a	CLKOUT to $\overline{TA}$ , $\overline{BI}$ High-Z (when driven by the memory controller or PCMCIA interface)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B14	CLKOUT to TEA assertion	2.50	10.00	2.50	10.00	2.50	10.00	2.50	9.00	ns
B15	CLKOUT to TEA High-Z	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B16	TA, BI valid to CLKOUT (setup time)	9.75		9.75		9.75	_	6.00	_	ns
B16a	TEA, KR, RETRY, CR valid to CLKOUT (setup time)	10.00	_	10.00	—	10.00	—	4.50	—	ns
B16b	$\overline{\text{BB}}, \overline{\text{BG}}, \overline{\text{BR}}, \text{ valid to CLKOUT (setup time)}^5$	8.50		8.50		8.50	_	4.00	_	ns
B17	CLKOUT to $\overline{TA}$ , $\overline{TEA}$ , $\overline{BI}$ , $\overline{BB}$ , $\overline{BG}$ , $\overline{BR}$ valid (hold time)	1.00	—	1.00	—	1.00	—	2.00	—	ns
B17a	CLKOUT to KR, RETRY, CR valid (hold time)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B18	D(0:31), DP(0:3) valid to CLKOUT rising edge (setup time) <sup>6</sup>	6.00	—	6.00	_	6.00	—	6.00	—	ns
B19	CLKOUT rising edge to D(0:31), DP(0:3) valid (hold time) <sup>6</sup>	1.00	—	1.00	—	1.00	—	2.00	—	ns
B20	D(0:31), DP(0:3) valid to CLKOUT falling edge (setup time) <sup>7</sup>	4.00	—	4.00	_	4.00	—	4.00	—	ns
B21	CLKOUT falling edge to D(0:31), DP(0:3) valid (hold time) <sup>7</sup>	2.00	—	2.00	—	2.00	—	2.00	—	ns
B22	CLKOUT rising edge to $\overline{CS}$ asserted GPCM ACS = 00	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.04	ns
B22a	CLKOUT falling edge to $\overline{CS}$ asserted GPCM ACS = 10, TRLX = 0		8.00		8.00		8.00		8.00	ns
B22b	CLKOUT falling edge to $\overline{CS}$ asserted GPCM ACS = 11, TRLX = 0, EBDF = 0	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.54	ns
B22c	CLKOUT falling edge to $\overline{CS}$ asserted GPCM ACS = 11, TRLX = 0, EBDF = 1	10.86	17.99	8.88	16.00	7.00	14.13	5.18	12.31	ns

## Table 7. Bus Operation Timings (continued)



	Characteristic	33	MHz	40 MHz		50 I	MHz	66 MHz		
Num	Characteristic	Min	Мах	Min	Max	Min	Мах	Min	Max	Unit
B23	CLKOUT rising edge to $\overline{CS}$ negated GPCM read access, GPCM write access ACS = 00, TRLX = 0, and CSNT = 0	2.00	8.00	2.00	8.00	2.00	8.00	2.00	8.00	ns
B24	A(0:31) and BADDR(28:30) to $\overline{CS}$ asserted GPCM ACS = 10, TRLX = 0	5.58	—	4.25	_	3.00	_	1.79	—	ns
B24a	A(0:31) and BADDR(28:30) to $\overline{CS}$ asserted GPCM ACS = 11, TRLX = 0	13.15	—	10.50	—	8.00	—	5.58	—	ns
B25	CLKOUT rising edge to $\overline{OE}$ , $\overline{WE}$ (0:3) asserted	—	9.00	—	9.00	—	9.00	—	9.00	ns
B26	CLKOUT rising edge to OE negated	2.00	9.00	2.00	9.00	2.00	9.00	2.00	9.00	ns
B27	A(0:31) and BADDR(28:30) to $\overline{CS}$ asserted GPCM ACS = 10, TRLX = 1	35.88	_	29.25	_	23.00	_	16.94	_	ns
B27a	A(0:31) and BADDR(28:30) to $\overline{CS}$ asserted GPCM ACS = 11, TRLX = 1	43.45	—	35.50	—	28.00	—	20.73	—	ns
B28	CLKOUT rising edge to $\overline{WE}(0:3)$ negated GPCM write access CSNT = 0	—	9.00	—	9.00	—	9.00	—	9.00	ns
B28a	CLKOUT falling edge to $\overline{WE}(0:3)$ negated GPCM write access TRLX = 0, 1, CSNT = 1, EBDF = 0	7.58	14.33	6.25	13.00	5.00	11.75	3.80	10.54	ns
B28b	CLKOUT falling edge to $\overline{CS}$ negated GPCM write access TRLX = 0, 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 0	—	14.33	—	13.00		11.75		10.54	ns
B28c	CLKOUT falling edge to $\overline{WE}$ (0:3) negated GPCM write access TRLX = 0, 1, CSNT = 1 write access TRLX = 0, CSNT = 1, EBDF = 1	10.86	17.99	8.88	16.00	7.00	14.13	5.18	12.31	ns
B28d	CLKOUT falling edge to $\overline{CS}$ negated GPCM write access TRLX = 0, 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 1	_	17.99	_	16.00		14.13		12.31	ns
B29	$\overline{WE}(0:3)$ negated to D(0:31), DP(0:3) High-Z GPCM write access CSNT = 0, EBDF = 0	5.58	_	4.25	—	3.00	—	1.79	—	ns
B29a	$\overline{WE}(0:3)$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 0, CSNT = 1, EBDF = 0	13.15	—	10.5	—	8.00		5.58	—	ns
B29b	$\overline{\text{CS}}$ negated to D(0:31), DP(0:3), High-Z GPCM write access, ACS = 00, TRLX = 0, 1, and CSNT = 0	5.58		4.25		3.00		1.79		ns
B29c	$\overline{\text{CS}}$ negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 0, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 0	13.15		10.5		8.00		5.58		ns

## Table 7. Bus Operation Timings (continued)



	Characteristic	33	MHz	40 MHz		50 MHz		66 MHz		11
NUM		Min	Max	Min	Max	Min	Max	Min	Max	Unit
B35	A(0:31), BADDR(28:30) to $\overline{CS}$ valid—as requested by control bit BST4 in the corresponding word in UPM	5.58	_	4.25	_	3.00	_	1.79	_	ns
B35a	A(0:31), BADDR(28:30), and D(0:31) to $\overline{\text{BS}}$ valid—as requested by control bit BST1 in the corresponding word in UPM	13.15	—	10.50	—	8.00	—	5.58	_	ns
B35b	A(0:31), BADDR(28:30), and D(0:31) to $\overline{\text{BS}}$ valid—as requested by control bit BST2 in the corresponding word in UPM	20.73	—	16.75	—	13.00	—	9.36		ns
B36	A(0:31), BADDR(28:30), and D(0:31) to GPL valid—as requested by control bit GxT4 in the corresponding word in UPM	5.58	—	4.25	—	3.00	—	1.79	_	ns
B37	UPWAIT valid to CLKOUT falling edge <sup>9</sup>	6.00	—	6.00	—	6.00	—	6.00		ns
B38	CLKOUT falling edge to UPWAIT valid <sup>9</sup>	1.00	—	1.00	_	1.00	_	1.00	_	ns
B39	AS valid to CLKOUT rising edge <sup>10</sup>	7.00	_	7.00	_	7.00	_	7.00	_	ns
B40	A(0:31), TSIZ(0:1), RD/WR, BURST, valid to CLKOUT rising edge	7.00	—	7.00	—	7.00	—	7.00	_	ns
B41	$\overline{\text{TS}}$ valid to CLKOUT rising edge (setup time)	7.00	—	7.00	_	7.00	_	7.00	_	ns
B42	CLKOUT rising edge to $\overline{TS}$ valid (hold time)	2.00	—	2.00	—	2.00	—	2.00	_	ns
B43	AS negation to memory controller signals negation	_	TBD	_	TBD	_	TBD	_	TBD	ns

<sup>1</sup> Phase and frequency jitter performance results are only valid if the input jitter is less than the prescribed value.

<sup>2</sup> If the rate of change of the frequency of EXTAL is slow (that is, it does not jump between the minimum and maximum values in one cycle) or the frequency of the jitter is fast (that is, it does not stay at an extreme value for a long time) then the maximum allowed jitter on EXTAL can be up to 2%.

<sup>3</sup> The timings specified in B4 and B5 are based on full strength clock.

<sup>4</sup> The timing for BR output is relevant when the MPC860 is selected to work with external bus arbiter. The timing for BG output is relevant when the MPC860 is selected to work with internal bus arbiter.

<sup>5</sup> The timing required for BR input is relevant when the MPC860 is selected to work with internal bus arbiter. The timing for BG input is relevant when the MPC860 is selected to work with external bus arbiter.

<sup>6</sup> The D(0:31) and DP(0:3) input timings B18 and B19 refer to the rising edge of the CLKOUT in which the TA input signal is asserted.

<sup>7</sup> The D(0:31) and DP(0:3) input timings B20 and B21 refer to the falling edge of the CLKOUT. This timing is valid only for read accesses controlled by chip-selects under control of the UPM in the memory controller, for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

<sup>8</sup> The timing B30 refers to  $\overline{CS}$  when ACS = 00 and to  $\overline{WE}(0:3)$  when CSNT = 0.

<sup>9</sup> The signal UPWAIT is considered asynchronous to the CLKOUT and synchronized internally. The timings specified in B37 and B38 are specified to enable the freeze of the UPM output signals as described in Figure 18.

<sup>10</sup> The AS signal is considered asynchronous to the CLKOUT. The timing B39 is specified in order to allow the behavior specified in Figure 21.





Figure 15. External Bus Write Timing (GPCM Controlled—TRLX = 0 or 1, CSNT = 1)







Figure 17. External Bus Timing (UPM Controlled Signals)



1

Table 8 provides interrupt timing for the MPC860.

### Table 8. Interrupt Timing

Num	Characteristic1	All Freq	Unit	
	Characteristic	Min	Мах	Onit
139	IRQx valid to CLKOUT rising edge (setup time)	6.00	_	ns
140	IRQx hold time after CLKOUT	2.00	_	ns
141	IRQx pulse width low	3.00	—	ns
142	IRQx pulse width high	3.00	_	ns
143	IRQx edge-to-edge time	$4 \times T_{CLOCKOUT}$	—	—

The timings I39 and I40 describe the testing conditions under which the IRQ lines are tested when being defined as level-sensitive. The IRQ lines are synchronized internally and do not have to be asserted or negated with reference to the CLKOUT.

The timings I41, I42, and I43 are specified to allow the correct function of the IRQ lines detection circuitry and have no direct relation with the total system interrupt latency that the MPC860 is able to support.

Figure 23 provides the interrupt detection timing for the external level-sensitive lines.



Figure 23. Interrupt Detection Timing for External Level Sensitive Lines

Figure 24 provides the interrupt detection timing for the external edge-sensitive lines.



Figure 24. Interrupt Detection Timing for External Edge Sensitive Lines



## Table 9 shows the PCMCIA timing for the MPC860.

Table 9. PCMCIA Timing

Num	Characteristic		MHz	40 I	MHz	50 I	MHz	66 I	MHz	11
Num	Characteristic	Min	Max	Min	Max	Min	Max	Min	Max	Unit
P44	A(0:31), REG valid to PCMCIA Strobe asserted <sup>1</sup>	20.73	—	16.75	—	13.00	—	9.36	—	ns
P45	A(0:31), $\overline{\text{REG}}$ valid to ALE negation <sup>1</sup>	28.30	—	23.00	—	18.00	—	13.15	_	ns
P46	CLKOUT to REG valid	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P47	CLKOUT to REG invalid	8.58	—	7.25	—	6.00	—	4.84	_	ns
P48	CLKOUT to $\overline{CE1}$ , $\overline{CE2}$ asserted	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P49	CLKOUT to $\overline{CE1}$ , $\overline{CE2}$ negated	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P50	CLKOUT to PCOE, IORD, PCWE, IOWR assert time	—	11.00		11.00	—	11.00	—	11.00	ns
P51	CLKOUT to PCOE, IORD, PCWE, IOWR negate time	2.00	11.00	2.00	11.00	2.00	11.00	2.00	11.00	ns
P52	CLKOUT to ALE assert time	7.58	15.58	6.25	14.25	5.00	13.00	3.79	10.04	ns
P53	CLKOUT to ALE negate time	—	15.58		14.25	_	13.00	—	11.84	ns
P54	PCWE, IOWR negated to D(0:31) invalid <sup>1</sup>	5.58	—	4.25	—	3.00	—	1.79	_	ns
P55	WAITA and WAITB valid to CLKOUT rising edge <sup>1</sup>	8.00	—	8.00	—	8.00	—	8.00	—	ns
P56	CLKOUT rising edge to WAITA and WAITB invalid <sup>1</sup>	2.00	—	2.00	—	2.00	—	2.00	—	ns

<sup>1</sup> PSST = 1. Otherwise add PSST times cycle time.

PSHT = 0. Otherwise add PSHT times cycle time.

These synchronous timings define when the WAITx signals are detected in order to freeze (or relieve) the PCMCIA current cycle. The WAITx assertion will be effective only if it is detected 2 cycles before the PSL timer expiration. See Chapter 16, "PCMCIA Interface," in the *MPC860 PowerQUICCTM Family User's Manual*.







Figure 26. PCMCIA Access Cycle Timing External Bus Write

Figure 27 provides the PCMCIA  $\overline{WAIT}$  signal detection timing.



Figure 27. PCMCIA WAIT Signal Detection Timing





Figure 47. SDACK Timing Diagram—Peripheral Write, Internally-Generated TA



Figure 48. SDACK Timing Diagram—Peripheral Read, Internally-Generated TA



Num	Characteristic	All Freq	Unit	
Nulli	Characteristic	Min	Мах	Onit
84	L1CLK edge to L1CLKO valid (DSC = 1)	—	30.00	ns
85	L1RQ valid before falling edge of L1TSYNC <sup>4</sup>	1.00	_	L1TCL K
86	L1GR setup time <sup>2</sup>	42.00	—	ns
87	L1GR hold time	42.00	—	ns
88	L1CLK edge to L1SYNC valid (FSD = 00) CNT = 0000, BYT = 0, DSC = 0)	—	0.00	ns

### Table 19. SI Timing (continued)

<sup>1</sup> The ratio SYNCCLK/L1RCLK must be greater than 2.5/1.

<sup>2</sup> These specs are valid for IDL mode only.

<sup>3</sup> Where P = 1/CLKOUT. Thus, for a 25-MHz CLKO1 rate, P = 40 ns.

<sup>4</sup> These strobes and TxD on the first bit of the frame become valid after L1CLK edge or L1SYNC, whichever comes later.



Figure 51. SI Receive Timing Diagram with Normal Clocking (DSC = 0)





MPC860 PowerQUICC Family Hardware Specifications, Rev. 10



#### SCC in NMSI Mode Electrical Specifications 11.7

Table 20 provides the NMSI external clock timing.

Table 2	20. NMSI	External	Clock	Timing
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Num	Characteristic	All Freq	Unit	
Nulli	Characteristic	Min	Мах	Unit
100	RCLK1 and TCLK1 width high <sup>1</sup>	1/SYNCCLK	_	ns
101	RCLK1 and TCLK1 width low	1/SYNCCLK + 5		ns
102	RCLK1 and TCLK1 rise/fall time	—	15.00	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	50.00	ns
104	RTS1 active/inactive delay (from TCLK1 falling edge)	0.00	50.00	ns
105	CTS1 setup time to TCLK1 rising edge	5.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	5.00	_	ns
107	RXD1 hold time from RCLK1 rising edge <sup>2</sup>	5.00	—	ns
108	CD1 setup Time to RCLK1 rising edge	5.00	_	ns

<sup>1</sup> The ratios SYNCCLK/RCLK1 and SYNCCLK/TCLK1 must be greater than or equal to 2.25/1.
 <sup>2</sup> Also applies to CD and CTS hold time when they are used as external sync signals.

## Table 21 provides the NMSI internal clock timing.

## Table 21. NMSI Internal Clock Timing

Num	Characteristic	All Freq	Unit	
Num	Characteristic	Min	Мах	Unit
100	RCLK1 and TCLK1 frequency <sup>1</sup>	0.00	SYNCCLK/3	MHz
102	RCLK1 and TCLK1 rise/fall time	—	—	ns
103	TXD1 active delay (from TCLK1 falling edge)	0.00	30.00	ns
104	RTS1 active/inactive delay (from TCLK1 falling edge)	0.00	30.00	ns
105	CTS1 setup time to TCLK1 rising edge	40.00	—	ns
106	RXD1 setup time to RCLK1 rising edge	40.00	—	ns
107	RXD1 hold time from RCLK1 rising edge <sup>2</sup>	0.00	_	ns
108	CD1 setup time to RCLK1 rising edge	40.00	_	ns

<sup>1</sup> The ratios SYNCCLK/RCLK1 and SYNCCLK/TCLK1 must be greater than or equal to 3/1.

<sup>2</sup> Also applies to  $\overline{CD}$  and  $\overline{CTS}$  hold time when they are used as external sync signals.







# 11.12 I<sup>2</sup>C AC Electrical Specifications

Table 26 provides the  $I^2C$  (SCL < 100 kHz) timings.

## Table 26. I<sup>2</sup>C Timing (SCL < 100 kHz)

Num	Characteristic	All Frequencies		Unit	
Nulli			Мах	Unit	
200	SCL clock frequency (slave)	0	100	kHz	
200	SCL clock frequency (master) <sup>1</sup>	1.5	100	kHz	
202	Bus free time between transmissions	4.7	—	μS	
203	Low period of SCL	4.7	—	μS	
204	High period of SCL	4.0	—	μS	
205	Start condition setup time	4.7	—	μS	
206	Start condition hold time	4.0	—	μS	
207	Data hold time	0	—	μS	
208	Data setup time	250	—	ns	
209	SDL/SCL rise time	—	1	μS	
210	SDL/SCL fall time	—	300	ns	
211	Stop condition setup time	4.7	—	μS	

SCL frequency is given by SCL = BRGCLK\_frequency / ((BRG register + 3 × pre\_scaler × 2). The ratio SYNCCLK/(BRGCLK/pre\_scaler) must be greater than or equal to 4/1.

## Table 27 provides the $I^2C$ (SCL > 100 kHz) timings.

## Table 27. . I<sup>2</sup>C Timing (SCL > 100 kHz)

Num	Characteristic	Expression	All Freq	Unit		
Num	Characteristic	Expression	Min	Мах	Unit	
200	SCL clock frequency (slave)	fSCL	0	BRGCLK/48	Hz	
200	SCL clock frequency (master) <sup>1</sup>	fSCL	BRGCLK/16512	BRGCLK/48	Hz	
202	Bus free time between transmissions		1/(2.2 * fSCL)	—	S	
203	Low period of SCL		1/(2.2 * fSCL)	—	S	
204	High period of SCL		1/(2.2 * fSCL)	—	S	
205	Start condition setup time		1/(2.2 * fSCL)	—	S	
206	Start condition hold time		1/(2.2 * fSCL)	—	S	
207	Data hold time		0	—	S	
208	Data setup time		1/(40 * fSCL)	—	S	
209	SDL/SCL rise time		—	1/(10 * fSCL)	S	
210	SDL/SCL fall time		—	1/(33 * fSCL)	S	
211	Stop condition setup time		1/2(2.2 * fSCL)	—	s	

SCL frequency is given by SCL = BRGCLK\_frequency / ((BRG register + 3) × pre\_scaler × 2). The ratio SYNCCLK/(BRGCLK / pre\_scaler) must be greater than or equal to 4/1.



## 13.3 MII Async Inputs Signal Timing (MII\_CRS, MII\_COL)

Table 31 provides information on the MII async inputs signal timing.

Table 31. MII Async Inputs Signal Timing

Num	Characteristic	Min	Мах	Unit
M9	MII_CRS, MII_COL minimum pulse width	1.5		MII_TX_CLK period

Figure 74 shows the MII asynchronous inputs signal timing diagram.



## 13.4 MII Serial Management Channel Timing (MII\_MDIO, MII\_MDC)

Table 32 provides information on the MII serial management channel signal timing. The FEC functions correctly with a maximum MDC frequency in excess of 2.5 MHz. The exact upper bound is under investigation.

Num	Characteristic	Min	Мах	Unit
M10	MII_MDC falling edge to MII_MDIO output invalid (minimum propagation delay)	0	_	ns
M11	MII_MDC falling edge to MII_MDIO output valid (max prop delay)	_	25	ns
M12	MII_MDIO (input) to MII_MDC rising edge setup	10	—	ns
M13	MII_MDIO (input) to MII_MDC rising edge hold	0	—	ns
M14	MII_MDC pulse width high	40%	60%	MII_MDC period
M15	MII_MDC pulse width low	40%	60%	MII_MDC period

### Table 32. MII Serial Management Channel Timing



#### Mechanical Data and Ordering Information

Figure 75 shows the MII serial management channel timing diagram.



Figure 75. MII Serial Management Channel Timing Diagram

# 14 Mechanical Data and Ordering Information

## 14.1 Ordering Information

Table 33 provides information on the MPC860 Revision D.4 derivative devices.

Device	Number of SCCs <sup>1</sup>	Ethernet Support <sup>2</sup> (Mbps)	Multichannel HDLC Support	ATM Support
MPC855T	1	10/100	Yes	Yes
MPC860DE	2	10	N/A	N/A
MPC860DT		10/100	Yes	Yes
MPC860DP		10/100	Yes	Yes
MPC860EN	4	10	N/A	N/A
MPC860SR		10	Yes	Yes
MPC860T		10/100	Yes	Yes
MPC860P		10/100	Yes	Yes

Table 33. MPC860 Family Revision D.4 Derivatives

<sup>1</sup> Serial communications controller (SCC)

<sup>2</sup> Up to 4 channels at 40 MHz or 2 channels at 25 MHz



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